

NCE N-Channel Super Trench II Power MOSFET

Description

The series of devices uses Super Trench II technology that is uniquely optimized to provide the most efficient high frequency switching performance. Both conduction and switching power losses are minimized due to an extremely low combination of $R_{\text{DS}(\text{ON})}$ and $Q_g.$ This device is ideal for high-frequency switching and synchronous rectification.

Application

- DC/DC Converter
- •Ideal for high-frequency switching synchronous rectification

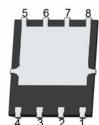
General Features

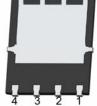
- V_{DS} =85V,I_D =100A $R_{DS(ON)}$ =4.6m Ω , typical @ V_{GS} =10V
- Excellent gate charge x R_{DS(on)} product(FOM)
- Very low on-resistance R_{DS(on)}
- 150°C operating temperature
- Pb-free lead plating

100% UIS TESTED! 100% AVds TESTED!

DFN5X6

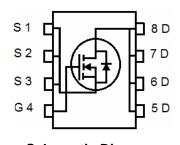






Top View

Bottom View



Schematic Diagram

Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity
P050N85G	NCEP050N85G	DFN5X6-8L	-	-	-

Absolute Maximum Ratings (T_A=25℃unless otherwise noted)

Parameter	Symbol	Limit	Unit
Drain-Source Voltage	V _{DS}	85	V
Gate-Source Voltage	V _{GS}	±20	V
Drain Current-Continuous	I _D	100	А
Drain Current-Continuous(T _C =100℃)	I _D (100℃)	75	Α
Pulsed Drain Current	I _{DM}	400	Α
Maximum Power Dissipation	P _D	125	W
Derating factor		1.0	W/℃
Single pulse avalanche energy (Note 5)	E _{AS}	540	mJ
Operating Junction and Storage Temperature Range	T_{J} , T_{STG}	-55 To 150	$^{\circ}$ C

Thermal Characteristic

The second Description	Thormal Posistance Junction to Case (Note 2)	Б	4.0	°C/W
	Thermal Resistance, Junction-to-Case (1986)	R _{θJC}	1.0	C/VV



Electrical Characteristics (T_C=25 °C unless otherwise noted)

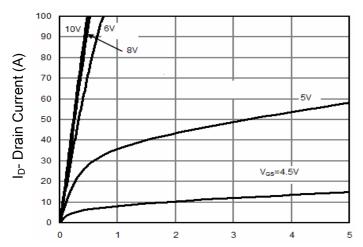
Parameter	Symbol	Condition	Min	Тур	Max	Unit
Off Characteristics						
Drain-Source Breakdown Voltage	BV _{DSS}	V _{GS} =0V I _D =250μA	85		-	V
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =85V,V _{GS} =0V	-	-	1	μA
Gate-Body Leakage Current	I _{GSS}	V_{GS} =±20 V , V_{DS} =0 V	-	-	±100	nA
On Characteristics (Note 3)	<u>.</u>		•			•
Gate Threshold Voltage	V _{GS(th)}	$V_{DS}=V_{GS},I_{D}=250\mu A$	2.0	3.0	4.0	V
Drain-Source On-State Resistance	R _{DS(ON)}	V _{GS} =10V, I _D =50A	-	4.6	5.0	mΩ
Forward Transconductance	g FS	V _{DS} =5V,I _D =50A		60	-	S
Dynamic Characteristics (Note4)						
Input Capacitance	C _{lss}	\/ 40\/\/ 0\/	-	3528	-	PF
Output Capacitance	Coss	V_{DS} =40V, V_{GS} =0V,	-	635	-	PF
Reverse Transfer Capacitance	C _{rss}	F=1.0MHz		11	-	PF
Switching Characteristics (Note 4)						
Turn-on Delay Time	t _{d(on)}		-	18	-	nS
Turn-on Rise Time	t _r	V_{DD} =40 V , I_{D} =50 A	-	17	-	nS
Turn-Off Delay Time	t _{d(off)}	V_{GS} =10 V , R_{G} =1.6 Ω	-	44	-	nS
Turn-Off Fall Time	t _f		-	11	-	nS
Total Gate Charge	Qg	\/ -40\/ -504	-	52	-	nC
Gate-Source Charge	Q _{gs}	V _{DS} =40V,I _D =50A,	-	14.0		nC
Gate-Drain Charge	Q _{gd}	V _{GS} =10V		13.2		nC
Drain-Source Diode Characteristics						
Diode Forward Voltage (Note 3)	V _{SD}	V _{GS} =0V,I _S =50A	-		1.2	V
Diode Forward Current (Note 2)	Is		-	-	100	Α
Reverse Recovery Time	t _{rr}	$T_J = 25^{\circ}C, I_F = I_S$	-	61	-	nS
Reverse Recovery Charge	Qrr	$di/dt = 100A/\mu s^{(Note3)}$	-	110	-	nC

Notes:

- 1. Repetitive Rating: Pulse width limited by maximum junction temperature.
- 2. Surface Mounted on FR4 Board, t ≤ 10 sec.
- 3. Pulse Test: Pulse Width \leq 300 μ s, Duty Cycle \leq 2%.
- 4. Guaranteed by design, not subject to production
- 5. EAS condition : Tj=25 $^{\circ}\text{C}$,V $_{\text{DD}}$ =40V ,V $_{\text{G}}$ =10V ,L=0.5mH ,Rg=25 Ω

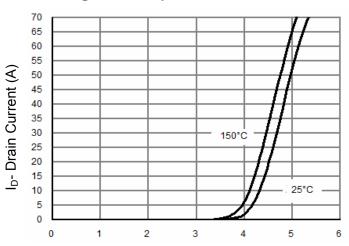


Typical Electrical and Thermal Characteristics



Vds Drain-Source Voltage (V)

Figure 1 Output Characteristics



Vgs Gate-Source Voltage (V)

Figure 2 Transfer Characteristics

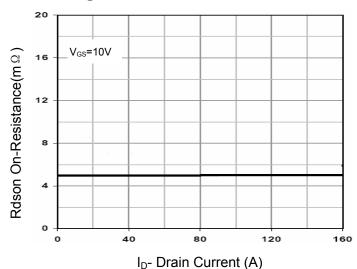
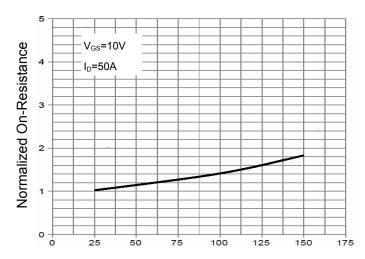
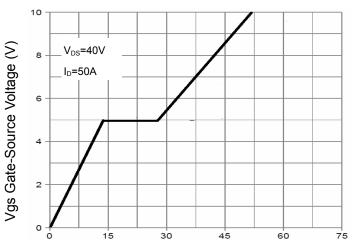


Figure 3 Rdson- Drain Current

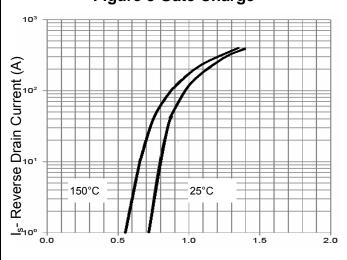


T_J-Junction Temperature(°C)

Figure 4 Rdson-Junction Temperature



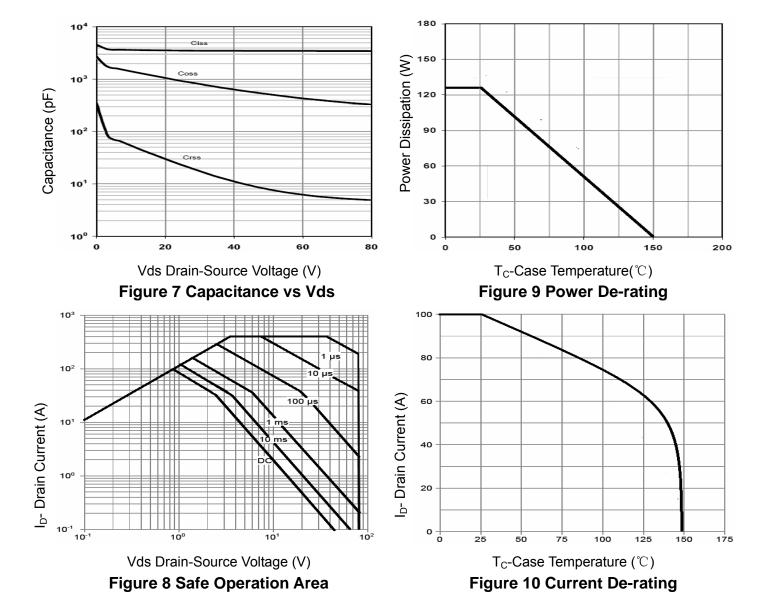
Qg Gate Charge (nC)
Figure 5 Gate Charge



Vsd Source-Drain Voltage (V)

Figure 6 Source- Drain Diode Forward





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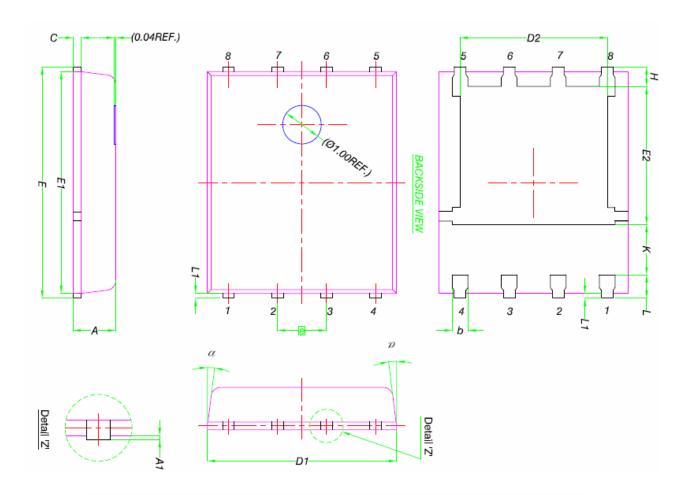
10²

Square Wave Pluse Duration(sec)

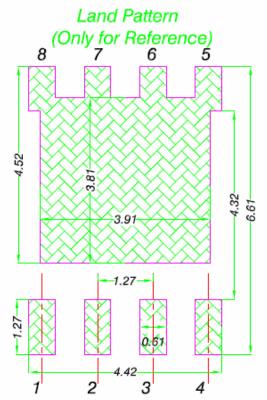
Figure 11 Normalized Maximum Transient Thermal Impedance



DFN5X6-8L Package Information



5/4	MILLIMETERS				
DIM.	MIN.	NOM.	MAX.		
Α	0.90	1.00	1.10		
A1	0	-	0.05		
b	0.33	0.41	0.51		
С	0.20	0.25	0.30		
D1	4.80	4.90	5.00		
D2	3.61	3.81	3.96		
Ε	5.90	6.00	6.10 5.80		
E1	5.70	5.75			
E2	3.38	3.58	3.78		
е					
Н	0.41	0.51	0.61		
K	K 1.10		-		
L	0.51	0.61	0.71		
L1	0.06	0.13	0.20		
α	<i>0</i> °	-	12°		





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